VS-GB300TH120N

Vishay Semiconductors

Molding Type Module IGBT, 2-in-1 Package, 1200 V and 300 A



Double	INT-A-PAK
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PRODUCT SUMMARY								
V _{CES}	1200 V							
I _C at T _C = 80 °C	300 A							
V _{CE(on)} (typical) at I _C = 300 A, 25 °C	2.00 V							
Speed	8 kHz to 30 kHz							
Package	Double INT-A-PAK							
Circuit	Half bridge							

FEATURES

- 10 µs short circuit capability
- V_{CE(on)} with positive temperature coefficient
- Maximum junction temperature 150 °C
- Low inductance case
- · Fast and soft reverse recovery antiparallel FWD
- Isolated copper baseplate using DCB (Direct Copper Bonding) technology
- · Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

TYPICAL APPLICATIONS

UPS

- Inverter for motor drive
- · AC and DC servo drive amplifier

DESCRIPTION

Vishay's IGBT power module provides ultra low conduction loss as well as short circuit ruggedness. It is designed for applications such as general inverters and UPS.

ABSOLUTE MAXIMUM RATINGS ($T_C = 25 \ ^{\circ}C$ unless otherwise noted)						
PARAMETER	ER SYMBOL		MAX.	UNITS		
Collector to emitter voltage	V _{CES}		1200	V		
Gate to emitter voltage	V _{GES}		± 20	v		
Collector current		T _C = 25 °C	500			
Collector current	Ic	T _C = 80 °C	300			
Pulsed collector current	I _{CM} ⁽¹⁾	t _p = 1 ms	600	А		
Diode continuous forward current	I _F	T _C = 80 °C	300			
Diode maximum forward current	I _{FM}	t _p = 1 ms	600			
Maximum power dissipation	PD	T _J = 150 °C	1645	W		
Short circuit withstand time	t _{SC}	T _J = 125 °C	10	μs		
RMS isolation voltage	V _{ISOL}	f = 50 Hz, t = 1 min	2500	V		

Note

⁽¹⁾ Repetitive rating: pulse width limited by maximum junction temperature.



COMPLIANT





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IGBT ELECTRICAL SPECIFICATIONS ($T_C = 25$ °C unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Collector to emitter breakdown voltage	V _{(BR)CES}	$T_J = 25 \ ^{\circ}C$	1200	-	-		
Collector to emitter voltage		V_{GE} = 15 V, I_C = 300 A, T_J = 25 $^\circ C$	-	2.00	2.45	v	
Collector to emitter voltage	V _{CE(on)}	$V_{GE} = 15 \text{ V}, \text{ I}_{C} = 300 \text{ A}, \text{ T}_{J} = 125 ^{\circ}\text{C}$	-	2.20	-	v	
Gate to emitter threshold voltage	V _{GE(th)}	V_{CE} = V_{GE} , I_C = 12 mA, T_J = 25 °C	5.0	6.2	7.0		
Collector cut-off current	I _{CES}	$V_{CE} = V_{CES}, V_{GE} = 0 \text{ V}, \text{T}_{\text{J}} = 25 ^{\circ}\text{C}$	-	-	5.0	mA	
Gate to emitter leakage current	I _{GES}	$V_{GE}=V_{GES},V_{CE}=0~V,T_{J}=25~^{\circ}C$	-	-	400	nA	

SWITCHING CHARACTERISTICS	5					
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Turn-on delay time	t _{d(on)}		-	574	-	
Rise time	t _r		-	133	-	
Turn-off delay time	t _{d(off)}	$V_{CC} = 600 \text{ V}, \text{ I}_{C} = 300 \text{ A}, \text{ R}_{g} = 4.7 \Omega,$	-	563	-	ns
Fall time	t _f	$V_{GE} = \pm 15 \text{ V}, \text{ T}_{\text{J}} = 25 \text{ °C}$	-	120	-	
Turn-on switching loss	E _{on}		-	23.9	-	
Turn-off switching loss	E _{off}		-	25.3	-	- mJ
Turn-on delay time	t _{d(on)}		-	604	-	
Rise time	tr		-	137	-	ns
Turn-off delay time	t _{d(off)}	$V_{CC} = 600 \text{ V}, \text{ I}_{C} = 300 \text{ A}, \text{ R}_{g} = 4.7 \Omega,$	-	629	-	
Fall time	t _f	V _{GE} = ± 15 V, T _J = 125 °C	-	167	-	
Turn-on switching loss	E _{on}		-	31.5	-	
Turn-off switching loss	E _{off}		-	35.9	-	- mJ
Input capacitance	C _{ies}		-	21.2	-	
Output capacitance	C _{oes}	V _{GE} = 0 V, V _{CE} = 25 V, f = 1.0 MHz	-	1.42	-	nF
Reverse transfer capacitance	C _{res}		-	0.94	-	1
SC data	I _{SC}	$\label{eq:tsc} \begin{array}{l} t_{sc} \leq 10 \; \mu s, \; V_{GE} = 15 \; V, \; T_{J} = 125 \; ^{\circ}C, \\ V_{CC} = 900 \; V, \; V_{CEM} \leq 1200 \; V \end{array}$	-	1800	-	А
Internal gate resistance	R _{gint}		-	1.0	-	Ω
Stray inductance	L _{CE}		-	-	20	nH
Module lead resistance, terminal to chip	R _{CC'+EE'}	T _C = 25 °C	-	0.35	-	mΩ

DIODE ELECTRICAL SPECIFICATIONS ($T_C = 25 \text{ °C}$ unless otherwise noted)								
PARAMETER	SYMBOL	TEST CONDIT	ONS	MIN.	TYP.	MAX.	UNITS	
Diode forward voltage	V _F	I _F = 300 A	T _J = 25 °C	-	1.82	2.25	v	
Diode forward voltage	۷F	$I_{\rm F} = 300 {\rm A}$	T _J = 125 °C	-	1.95	-	v	
Diode reverse recovery charge	0		T _J = 25 °C	-	20.2	-	μC	
Diode reverse recovery charge	Q _{rr}		T _J = 125 °C	-	40.1	-	μΟ	
Diede zoels reverse recevers every	1	$I_F = 300 \text{ A}, V_R = 600 \text{ V},$	T _J = 25 °C	-	170	-	•	
Diode peak reverse recovery current	I _{rr}	dl/dt = -2360 A/µs, V _{GE} = -15 V	T _J = 125 °C	-	250	-	A	
	E		T _J = 25 °C	-	8.2	-	ml	
Diode reverse recovery energy	E _{rec}		T _J = 125 °C	-	21.7	-	mJ	

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THERMAL AND MECHANICAL SPECIFICATIONS							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS	
Operating junction temperature ra	nge T _J		-	-	150	℃	
Storage temperature range	T _{STG}		-40	-	125		
Junction to case	BT		-	-	0.076		
	ode R _{thJC}		-	-	0.100	K/W	
Case to sink	R _{thCS}	Conductive grease applied	-	0.035	-		
Mounting torque		Power terminal screw: M6		2.5 to 5.0)	Nm	
Mounting torque		Mounting screw: M6	3.0 to 5.0)		
Weight				300		g	

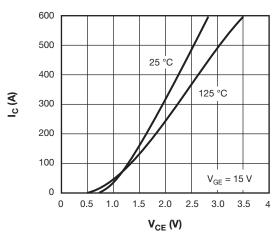


Fig. 1 - IGBT Typical Output Characteristics

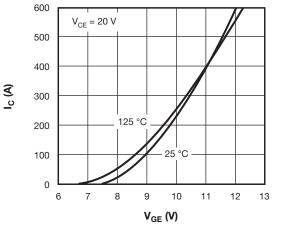
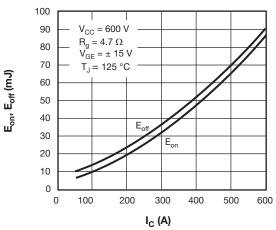
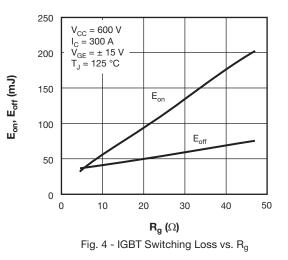


Fig. 2 - IGBT Typical Transfer Characteristics

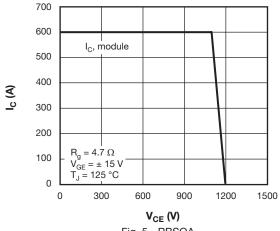




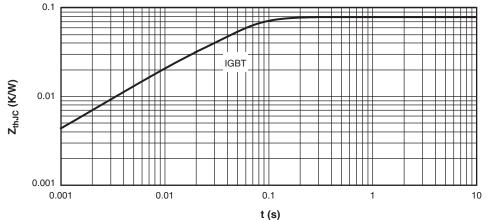


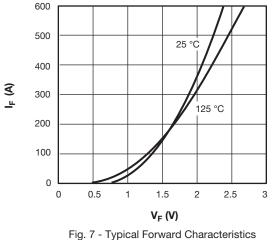
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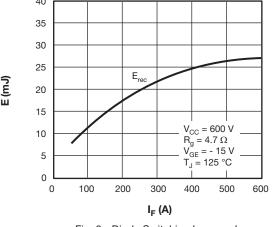


Fig. 8 - Diode Switching Loss vs. I_F

	Z _{thJ}																		
	0.00	0.001			0.01				 0.1					1			10		
					Fig.	6 - IG	ЪВТ	Tra	: (s) ent T	herm	al Imp	beda	ance	e					
600 500			25 °C								40 35 30								
400				$\not\mid$		-				~	25				E			_	+
300				125 °C	;	-				E (mJ)	20						-		+
200					_	-					15						V		† 0'



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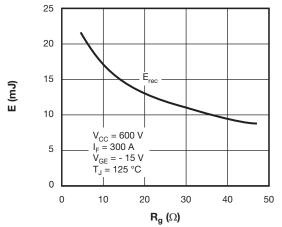
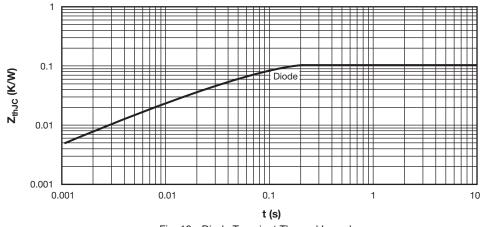
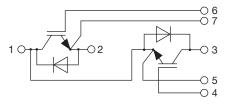


Fig. 9 - Diode Switching Loss vs. Gate Resistance Rg





CIRCUIT CONFIGURATION



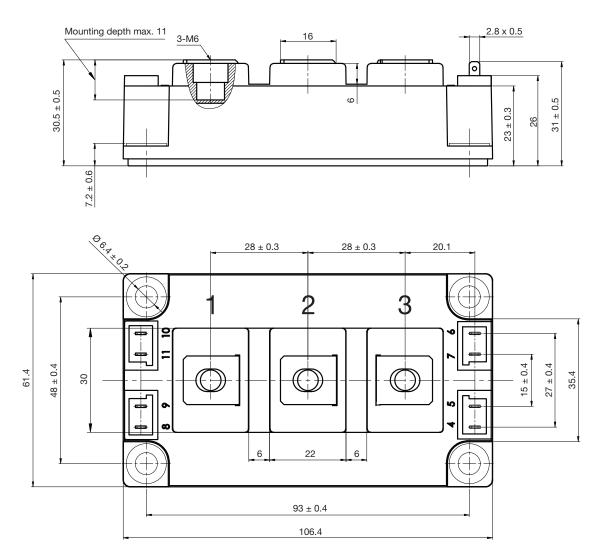
LINKS TO RELATED DOCUMENTS							
Dimensions	www.vishay.com/doc?95525						



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Double INT-A-PAK

DIMENSIONS in millimeters (inches)





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